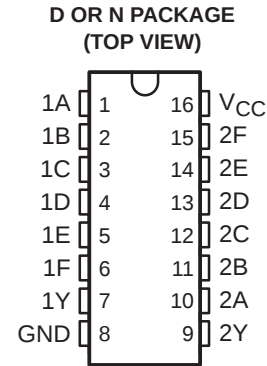


- Meets or Exceeds the Requirements of IBM™ System 360 Input/Output Interface Specification
- Operate From Single 5-V Supply
- TTL Compatible
- 3.11-V Output at $I_{OH} = -59.3 \text{ mA}$
- Uncommitted Emitter-Follower Output Structure for Party-Line Operation
- Short-Circuit Protection
- AND-OR Logic Configuration
- Designed for Use With Triple Line Receiver SN75124
- Designed to Be Interchangeable With N8T13 and N8T23



THE SN751730 IS RECOMMENDED
FOR NEW IBM 360/370 INTERFACE DESIGNS.

description

The SN75123 is a dual line driver specifically designed to meet the input/output interface specifications for IBM System 360. It also is compatible with standard-TTL logic and supply-voltage levels.

The SN75123 low-impedance emitter-follower outputs drive terminated lines such as coaxial cable or twisted pair. Having the outputs uncommitted allows wired-OR logic to be performed in party-line applications. Output short-circuit protection is provided by an internal clamping network that turns on when the output voltage drops below approximately 1.5 V. All the inputs are in conventional TTL configuration, and the gating can be used during power-up and power-down sequences to ensure that no noise is introduced to the line.

The SN75123 is characterized for operation from 0°C to 70°C.

FUNCTION TABLE

INPUTS						OUTPUT Y
A	B	C	D	E	F	
H	H	H	H	X	X	H
X	X	X	X	H	H	H
All other input combinations						L

H = high level, L = low level, X = irrelevant



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

IBM is a trademark of International Business Machines Corp.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



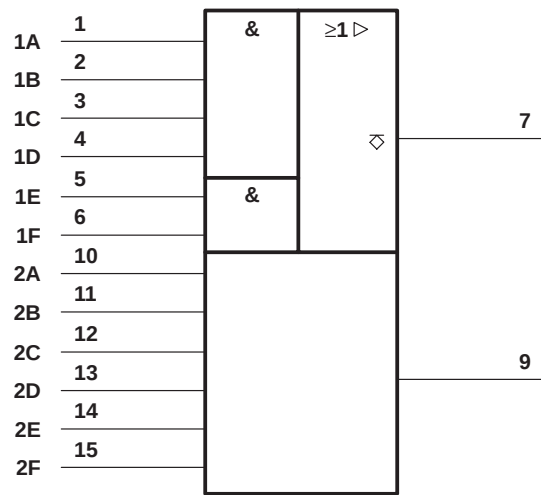
POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

Copyright © 1998, Texas Instruments Incorporated

SN75123
DUAL LINE DRIVER

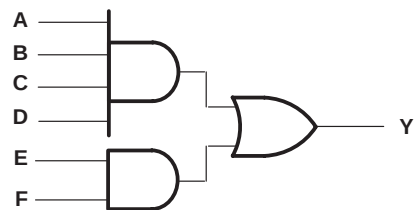
SLLS086C – SEPTEMBER 1973 – REVISED APRIL 1998

logic symbol†

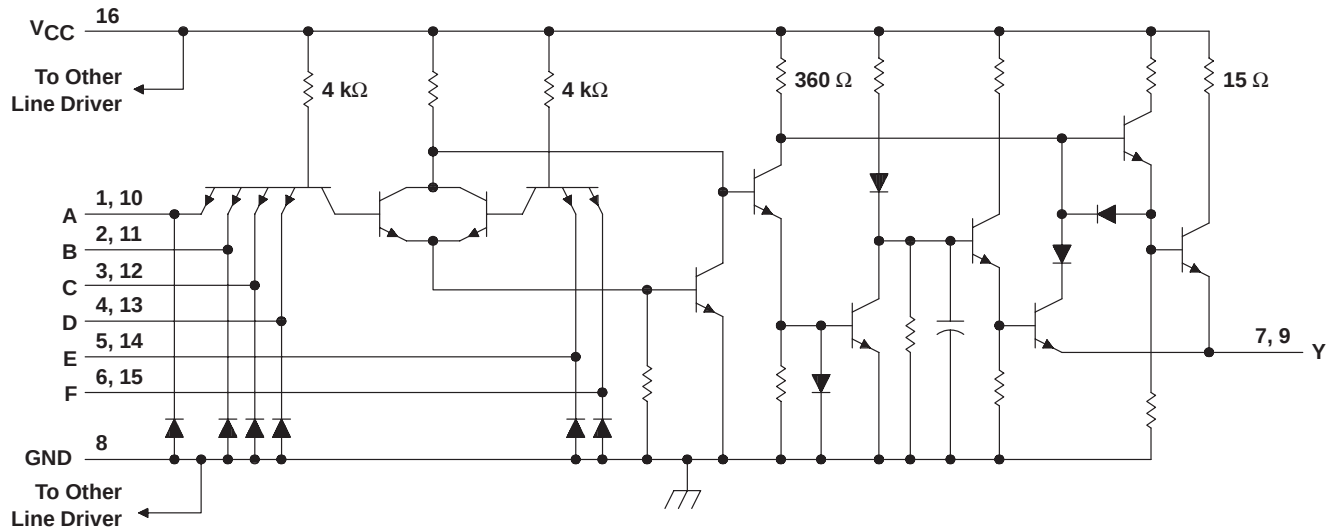


† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



schematic (each driver)



Resistor values shown are nominal.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage, V_{CC} (see Note 1)	7 V
Input voltage, V_I	5.5 V
Output voltage, V_O	7 V
Continuous total dissipation at (or below) 25°C free-air temperature (see Note 2): D package	950 mW
N package	1150 mW
Operating free-air temperature range, T_A	0°C to 70°C
Storage temperature range, T_{stg}	–65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltage values, except differential input voltage, are with respect to network ground terminal.

2. For operation above 25°C free-air temperature, derate the D package to 608 mW at 70°C at the rate of 7.6 mW/°C and the N package to 736 mW at 70°C at the rate of 9.2 mW/°C.

recommended operating conditions

	MIN	NOM	MAX	UNIT
Supply voltage, V_{CC}	4.75	5	5.25	V
High-level input voltage, V_{IH}	2			V
Low-level input voltage, V_{IL}			0.8	V
High-level output current, I_{OH}			–100	mA
Operating free-air temperature, T_A	0		70	°C

SN75123

DUAL LINE DRIVER

SLLS086C – SEPTEMBER 1973 – REVISED APRIL 1998

electrical characteristics, $V_{CC} = 4.75\text{ V to }5.25\text{ V}$, $T_A = 0^\circ\text{C to }70^\circ\text{C}$ (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	MAX	UNIT
V _{IK}	Input clamp voltage	V _{CC} = 5 V, I _I = −12 mA		−1.5		V
V _{I(BR)}	Input breakdown voltage	V _{CC} = 5 V, I _I = 10 mA		5.5		V
V _{OH}	High-level output voltage	V _{CC} = 5 V, V _{IH} = 2 V, I _{OH} = −59.3 mA, See Note 3	T _A = 25°C	3.11		V
			T _A = 0°C to 70°C	2.9		
V _{OL}	Low-level output voltage	V _{IL} = 0.8 V, I _{OL} = −240 μA, See Note 3		0.15		V
I _{OH}	High-level output current	V _{CC} = 5 V, V _{IH} = 4.5 V, V _{OH} = 2 V, T _A = 25°C, See Note 3		−100	−250	mA
I _{O(off)}	Off-state output current	V _{CC} = 0, V _O = 3 V		40		μA
I _{IH}	High-level input current	V _I = 4.5 V		40		μA
I _{IL}	Low-level input current	V _I = 0.4 V		−0.1	−1.6	mA
I _{OS}	Short-circuit output current†	V _{CC} = 5 V, T _A = 25°C		−30		mA
I _{CCH}	Supply current, outputs high	V _{CC} = 5.25 V,	All inputs at 2 V, Outputs open	28		mA
I _{CCL}	Supply current, outputs low	V _{CC} = 5.25 V,	All inputs at 0.8 V, Outputs open	60		mA

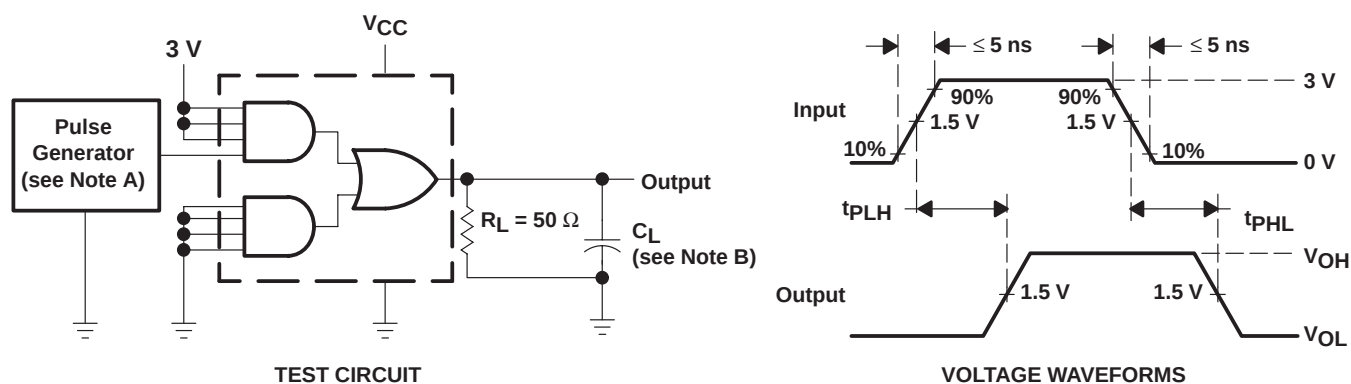
† Not more than one output should be shorted at a time.

NOTE 3: The output voltage and current limits are valid for any appropriate combination of high and low inputs specified by the function table for the desired output.

switching characteristics, $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{PLH} Propagation delay time, low- to high-level output	$R_L = 50\text{ }\Omega$, $C_L = 15\text{ pF}$, See Figure 1		12	20	ns
t_{PHL} Propagation delay time, high- to low-level output	$R_L = 50\text{ }\Omega$, $C_L = 15\text{ pF}$, See Figure 1		12	20	ns
t_{PLH} Propagation delay time, low- to high-level output	$R_L = 50\text{ }\Omega$, $C_L = 100\text{ pF}$, See Figure 1		20	35	ns
t_{PHL} Propagation delay time, high- to low-level output	$R_L = 50\text{ }\Omega$, $C_L = 100\text{ pF}$, See Figure 1		15	25	ns

PARAMETER MEASUREMENT INFORMATION



NOTES: A. The pulse generator has the following characteristics: $Z_O = 50\text{ }\Omega$, $t_W = 200\text{ ns}$, duty cycle = 50%.

B. C_L Includes probe and jig capacitance.

Figure 1. Test Circuit and Voltage Waveforms

TYPICAL CHARACTERISTICS

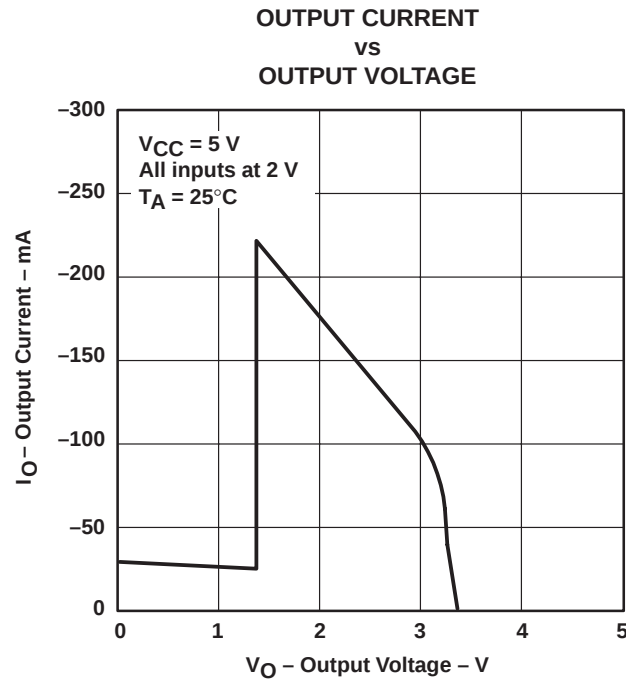


Figure 2

APPLICATION INFORMATION

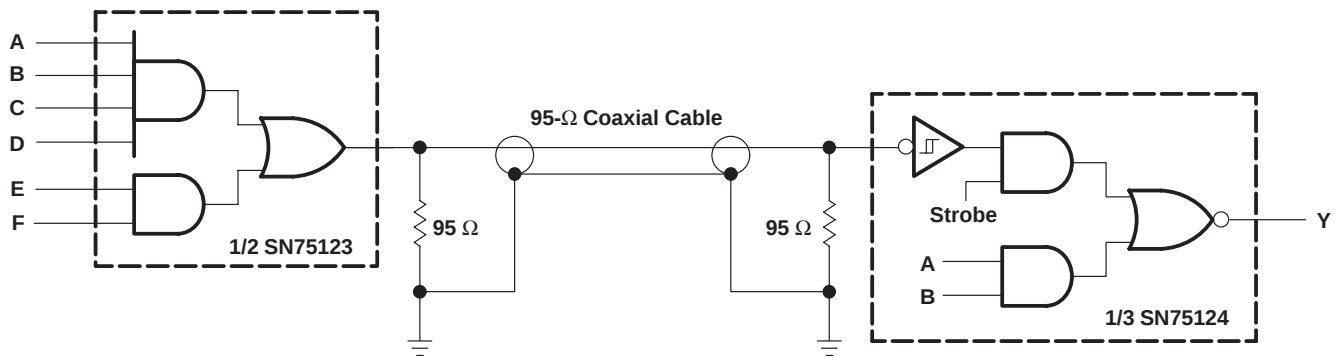


Figure 3. Unbalanced Line Communication Using SN75123 and SN75124

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
SN75123D	OBSOLETE	SOIC	D	16		TBD	Call TI	Call TI	Samples Not Available
SN75123DR	OBSOLETE	SOIC	D	16		TBD	Call TI	Call TI	Samples Not Available
SN75123N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	Contact TI Distributor or Sales Office
SN75123NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	Contact TI Distributor or Sales Office

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS-001 VARIATION	AA	BB	AC	AD

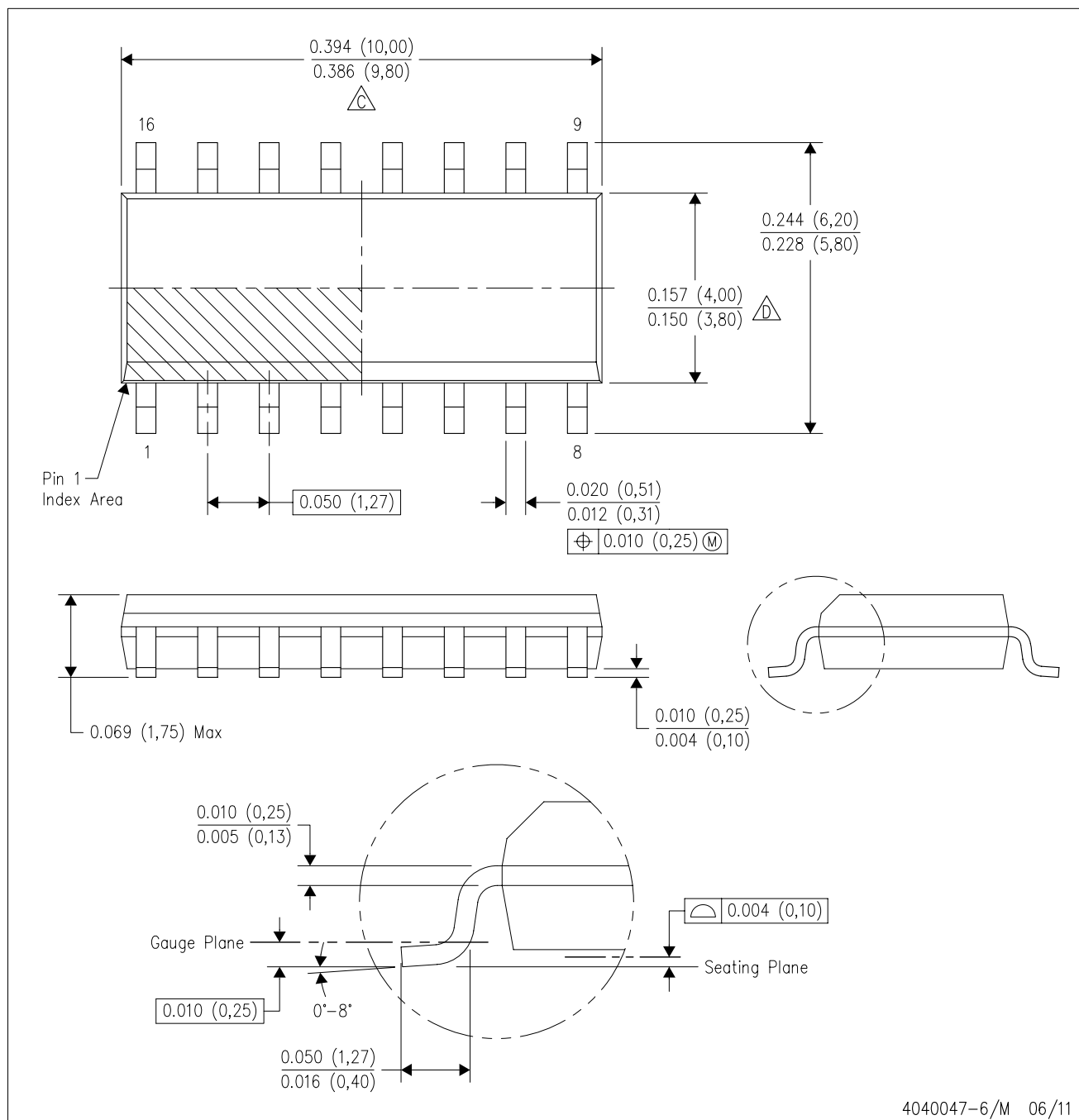


4040049/E 12/2002

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 -  Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 -  The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 -  C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
 -  D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
 - E. Reference JEDEC MS-012 variation AC.

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products

Audio	www.ti.com/audio
Amplifiers	amplifier.ti.com
Data Converters	dataconverter.ti.com
DLP® Products	www.dlp.com
DSP	dsp.ti.com
Clocks and Timers	www.ti.com/clocks
Interface	interface.ti.com
Logic	logic.ti.com
Power Mgmt	power.ti.com
Microcontrollers	microcontroller.ti.com
RFID	www.ti-rfid.com
RF/IF and ZigBee® Solutions	www.ti.com/lprf

Applications

Communications and Telecom	www.ti.com/communications
Computers and Peripherals	www.ti.com/computers
Consumer Electronics	www.ti.com/consumer-apps
Energy and Lighting	www.ti.com/energy
Industrial	www.ti.com/industrial
Medical	www.ti.com/medical
Security	www.ti.com/security
Space, Avionics and Defense	www.ti.com/space-avionics-defense
Transportation and Automotive	www.ti.com/automotive
Video and Imaging	www.ti.com/video
Wireless	www.ti.com/wireless-apps

TI E2E Community Home Page

e2e.ti.com

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
Copyright © 2011, Texas Instruments Incorporated